International Rectifier

AUIRF7484Q

HEXFET® Power MOSFET

Features

Advanced Planar Technology

- Low On-Resistance
- 150°C Operating Temperature
- Fast Switching
- Fully Avalanche Rated
- Repetitive Avalanche Allowed up to Tjmax
- Lead-Free, RoHS Compliant
- Automotive Qualified*

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V _{(BR)DSS}	40V
R _{DS(on)} max.	10m Ω
I _D	14A

Description

Specifically designed for Automotive applications, this Stripe Planar design of HEXFET® Power MOSFETs utilizes the latest processing techniques to achieve low on-resistance per silicon area. This benefit combined with the fast switching speed and ruggedized device design that HEXFET power MOSFETs are well known for, provides the designer with an extremely efficient and reliable device for use in Automotive and a wide variety of other applications.



Absolute Maximum Ratings

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature (T_A) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
V_{DS}	Drain-Source Voltage	40	V
I _D @ T _A = 25°C	Continuous Drain Current	14	
I _D @ T _A = 70°C	Continuous Drain Current	11	Α
I _{DM}	Pulsed Drain Current ①	110	
P _D @T _A = 25°C	Power Dissipation ^③	2.5	W
	Linear Derating Factor	0.02	W/°C
V_{GS}	Gate-to-Source Voltage	± 8.0	V
E _{AS}	Single Pulse Avalanche Energy (Thermally Limited)	230	mJ
I _{AR}	Avalanche Current ①	See Fig. 16c, 16d, 19, 20	Α
E _{AR}	Repetitive Avalanche Energy ®		mJ
T_J	Operating Junction and	-55 to + 150	°C
T _{STG}	Storage Temperature Range		

Thermal Resistance

	Parameter	Тур.	Max.	Units
$R_{ heta JL}$	Junction-to-Drain Lead		20	°C/W
$R_{\theta JA}$	Junction-to-Ambient ③		50	°C/W

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^{*}Qualification standards can be found at http://www.irf.com/

Static Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
$V_{(BR)DSS}$	Drain-to-Source Breakdown Voltage	40			٧	$V_{GS} = 0V, I_D = 250\mu A$
$\Delta V_{(BR)DSS}/\Delta T_{J}$	Breakdown Voltage Temp. Coefficient		0.040		V/°C	Reference to 25°C, I _D = 1mA
R _{DS(on)}	Static Drain-to-Source On-Resistance			10	mΩ	$V_{GS} = 7.0V, I_D = 14A$ ②
V _{GS(th)}	Gate Threshold Voltage	1.0		2.0	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
gfs	Forward Transconductance	40			S	$V_{DS} = 10V, I_{D} = 14A$
I _{DSS}	Drain-to-Source Leakage Current			20		$V_{DS} = 40V, V_{GS} = 0V$
				250	μA	$V_{DS} = 32V, V_{GS} = 0V, T_{J} = 125^{\circ}C$
I _{GSS}	Gate-to-Source Forward Leakage			200	n 1	V _{GS} = 8.0V
	Gate-to-Source Reverse Leakage			-200	nA	$V_{GS} = -8.0V$

Dynamic Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Тур.	Max.	Units	Conditions
Q_g	Total Gate Charge		69	100		I _D = 14A
Q_{gs}	Gate-to-Source Charge		9.0		nC	$V_{DS} = 32V$
Q_{gd}	Gate-to-Drain ("Miller") Charge		16			$V_{GS} = 7.0V$
t _{d(on)}	Turn-On Delay Time		9.3			$V_{DD} = 20V$
t _r	Rise Time		5.0			I _D = 1.0A
t _{d(off)}	Turn-Off Delay Time		180		ns	$R_G = 6.2\Omega$
t _f	Fall Time		58			V _{GS} = 7.0V ②
C _{iss}	Input Capacitance		3520			$V_{GS} = 0V$
C _{oss}	Output Capacitance		660		pF	$V_{DS} = 25V$
C _{rss}	Reverse Transfer Capacitance		76			f = 1.0MHz

Diode Characteristics

	Parameter	Min.	Тур.	Max.	Units	Conditions
I _S	Continuous Source Current			2.3		MOSFET symbol
	(Body Diode)			_ 2.3	' A	showing the
I _{SM}	Pulsed Source Current			110	^	integral reverse
	(Body Diode) ①			- 110		p-n junction diode.
V_{SD}	Diode Forward Voltage			1.3	V	$T_J = 25^{\circ}C$, $I_S = 2.3A$, $V_{GS} = 0V$ ②
t _{rr}	Reverse Recovery Time		59	89		$T_J = 25^{\circ}C, I_F = 2.3A$
Q _{rr}	Reverse Recovery Charge		110	170	nC	di/dt = 100A/µs ②
t _{on}	Forward Turn-On Time	Intrinsic	turn-on	time is r	egligible	(turn-on is dominated by LS+LD)

Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width \leq 400 μ s; duty cycle \leq 2%.
- 3 Surface mounted on 1 in square Cu board.
- $\label{eq:loss_def} \begin{tabular}{ll} \b$
- ⑥ Limited by T_{Jmax}, see Fig.16c, 16d, 19, 20 for typical repetitive avalanche performance.

Qualification Information[†]

		Automotive (per AEC-Q101)			
Qualification Lo	evel	Comments: This part number(s) passed Automotive qualification. Industrial and Consumer qualification level is granted by extension of higher Automotive level.			
Moisture Sensit	tivity Level	SO-8	MSL1		
	Machine Model	Class M3 (+/- 300V) ^{††}			
		AEC-Q101-002			
	Human Body Model		Class H1C (+/- 2000V) ^{††}		
ESD		AEC-Q101-001			
	Charged Device Model	Class C5 (+/- 2000V) ^{††}			
		AEC-Q101-005			
RoHS Complian	nt	Yes			

[†] Qualification standards can be found at International Rectifier's web site: http://www.irf.com/

^{††} Highest passing voltage.

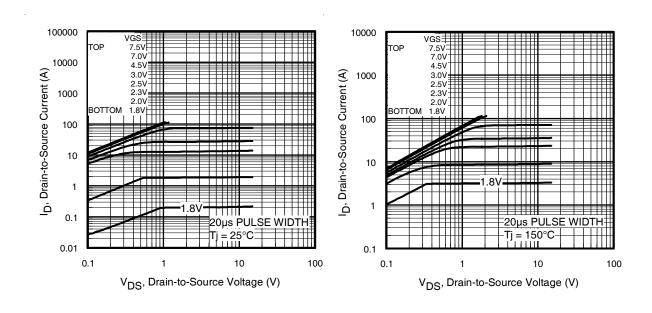


Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics

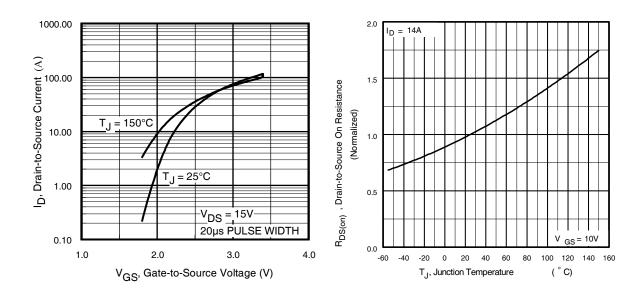
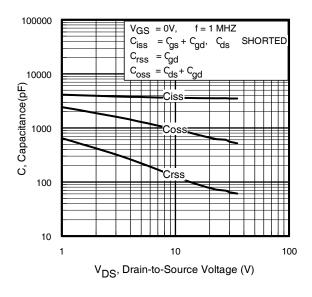


Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance Vs. Temperature



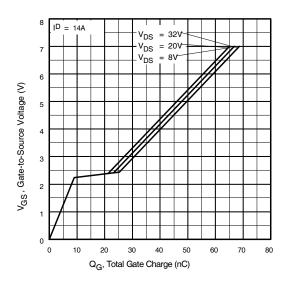


Fig 5. Typical Capacitance Vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge Vs. Gate-to-Source Voltage

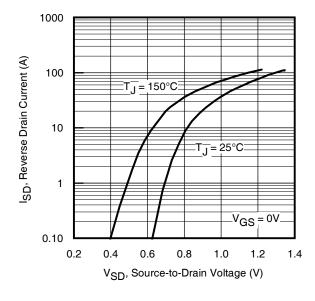


Fig 7. Typical Source-Drain Diode Forward Voltage

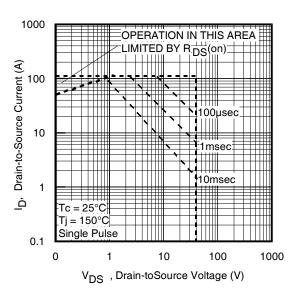


Fig 8. Maximum Safe Operating Area

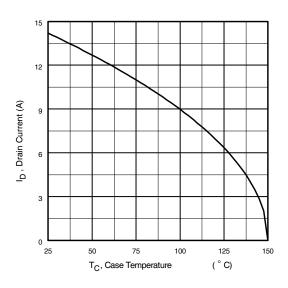


Fig 9. Maximum Drain Current Vs. Case Temperature

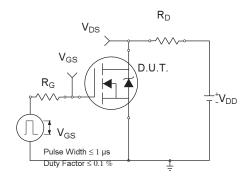


Fig 10a. Switching Time Test Circuit

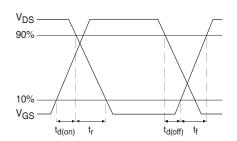


Fig 10b. Switching Time Waveforms

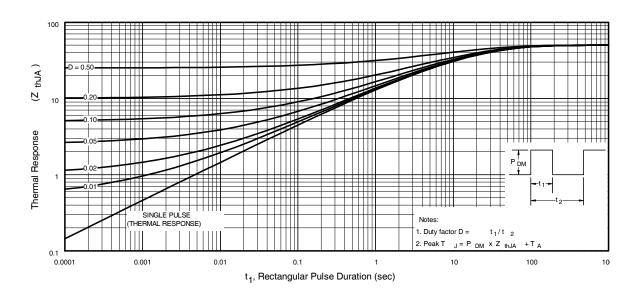
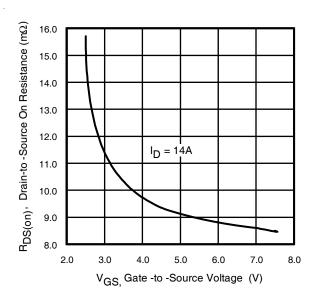


Fig 11. Typical Effective Transient Thermal Impedance, Junction-to-Ambient



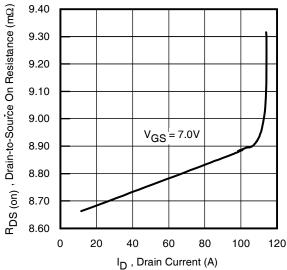
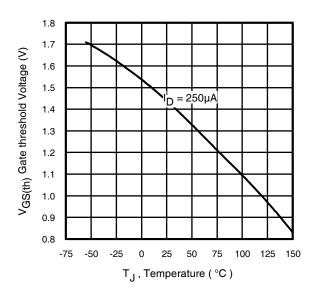


Fig 12. Typical On-Resistance Vs. Gate Voltage

Fig 13. Typical On-Resistance Vs. Drain Current



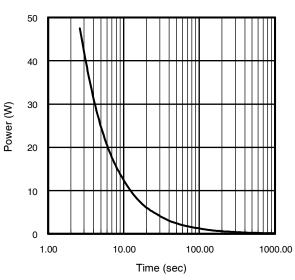
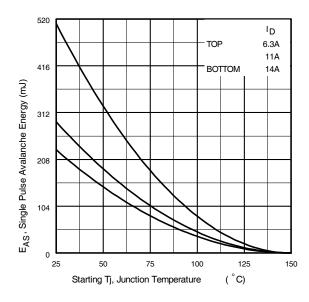


Fig 14. Typical Threshold Voltage Vs. Junction Temperature

Fig 15. Typical Power Vs. Time



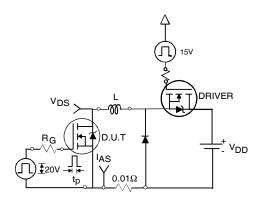


Fig 16c. Unclamped Inductive Test Circuit

Fig 16a. Maximum Avalanche Energy Vs. Drain Current

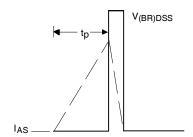


Fig 16d. Unclamped Inductive Waveforms

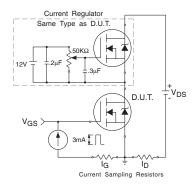


Fig 17. Gate Charge Test Circuit

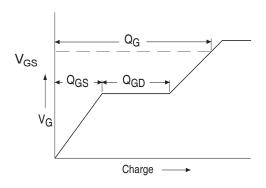


Fig 18. Basic Gate Charge Waveform

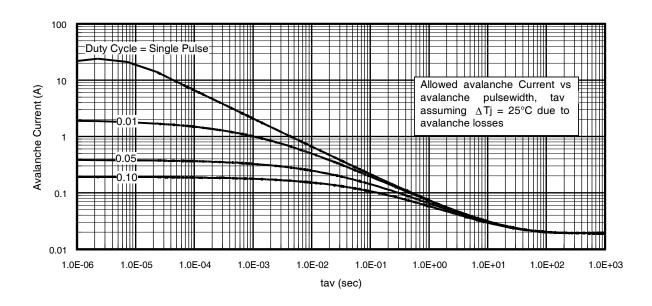


Fig 19. Typical Avalanche Current Vs.Pulsewidth

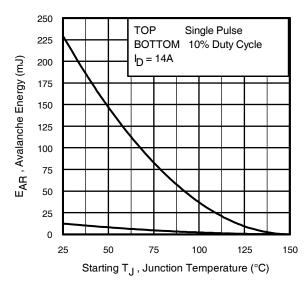


Fig 20. Maximum Avalanche Energy Vs. Temperature

Notes on Repetitive Avalanche Curves , Figures 15, 16: (For further info, see AN-1005 at www.irf.com)

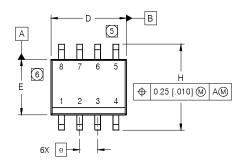
- 1. Avalanche failures assumption:
 - Purely a thermal phenomenon and failure occurs at a temperature far in excess of T_{jmax} . This is validated for every part type.
- Safe operation in Avalanche is allowed as long asT_{jmax} is not exceeded.
- 3. Equation below based on circuit and waveforms shown in Figures 12a, 12b.
- 4. $P_{D \text{ (ave)}}$ = Average power dissipation per single avalanche pulse.
- BV = Rated breakdown voltage (1.3 factor accounts for voltage increase during avalanche).
- 6. I_{av} = Allowable avalanche current.
- 7. ΔT = Allowable rise in junction temperature, not to exceed T_{jmax} (assumed as 25°C in Figure 15, 16). t_{av} = Average time in avalanche.
 - D = Duty cycle in avalanche = $t_{av} \cdot f$

 $Z_{th,JC}(D, t_{av})$ = Transient thermal resistance, see figure 11)

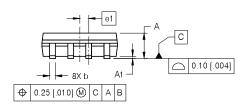
$$\begin{split} P_{D~(ave)} &= 1/2~(~1.3 \cdot BV \cdot I_{av}) = \triangle T/~Z_{thJC} \\ I_{av} &= 2\triangle T/~[1.3 \cdot BV \cdot Z_{th}] \\ E_{AS~(AR)} &= P_{D~(ave)} \cdot t_{av} \end{split}$$

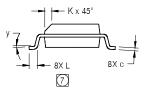
SO-8 Package Outline

Dimensions are shown in millimeters (inches)



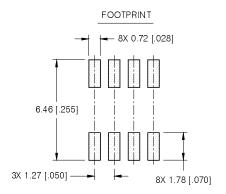
DIM	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	.0532	.0688	1.35	1.75
A1	.0040	.0098	0.10	0.25
b	.013	.020	0.33	0.51
O	.0075	.0098	0.19	0.25
D	.189	.1968	4.80	5.00
Е	.1497	.1574	3.80	4.00
е	.050 BASIC		1.27 BASIC	
e 1	.025 BASIC		0.635 I	BASIC
Η	.2284	.2440	5.80	6.20
K	.0099	.0196	0.25	0.50
L	.016	.050	0.40	1.27
У	0°	8°	0° 8°	



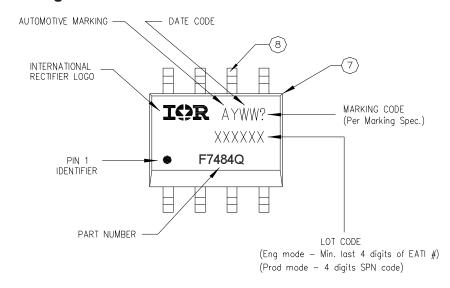


NOTES:

- 1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
- 2. CONTROLLING DIMENSION: MILLIMETER
- 3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 4. OUTLINE CONFORMS TO JEDEC OUTLINE MS-012AA.
- (5) DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.15 [.006].
- (6) DIMENSION DOES NOT INCLUDE MOLD PROTRUSIONS. MOLD PROTRUSIONS NOT TO EXCEED 0.25 [.010].
- [7] DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.



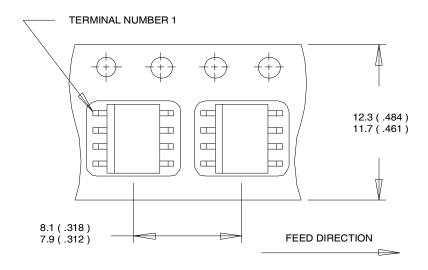
SO-8 Part Marking



Note: For the most current drawing please refer to IR website at http://www.irf.com/package/

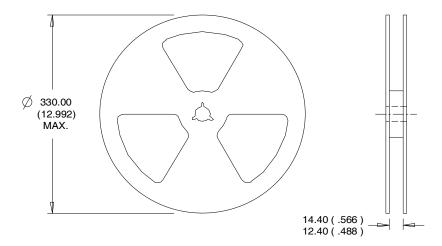
SO-8 Tape and Reel

Dimensions are shown in millimeters (inches)



NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER.
- 2. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS(INCHES).
- 3. OUTLINE CONFORMS TO EIA-481 & EIA-541.



NOTES:

- 1. CONTROLLING DIMENSION: MILLIMETER.
- 2. OUTLINE CONFORMS TO EIA-481 & EIA-541.

Ordering Information

Base part number	Package Type	Standard Pack		Complete Part Number
		Form	Quantity	
AUIRF7484Q	SO-8	Tube	95	AUIRF7484Q
		Tape and Reel	4000	AUIRF7484QTR

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